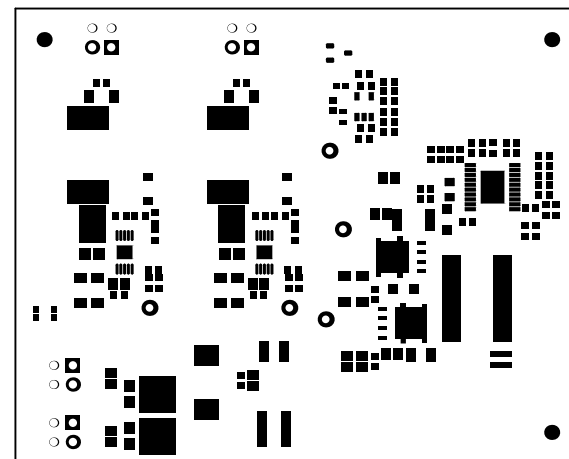
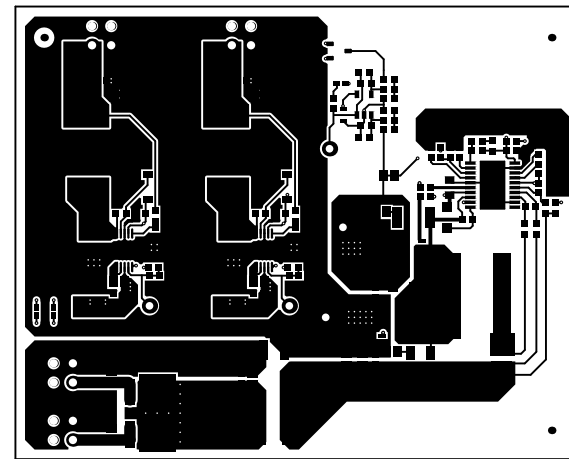


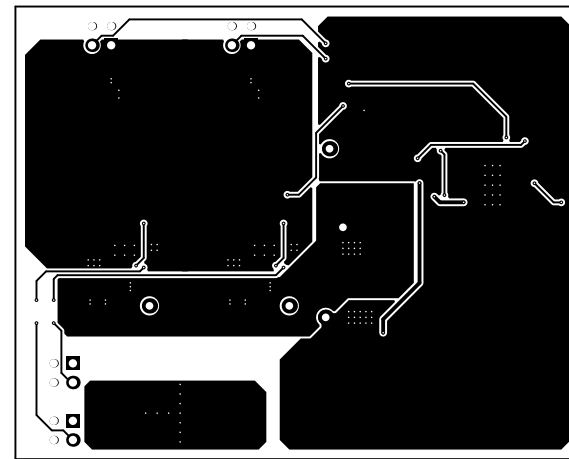
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01520	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01520		
PLOT NAME = Top Overlay	GENERATED : 12/12/2017 11:24:28 AM	TEXAS INSTRUMENTS	



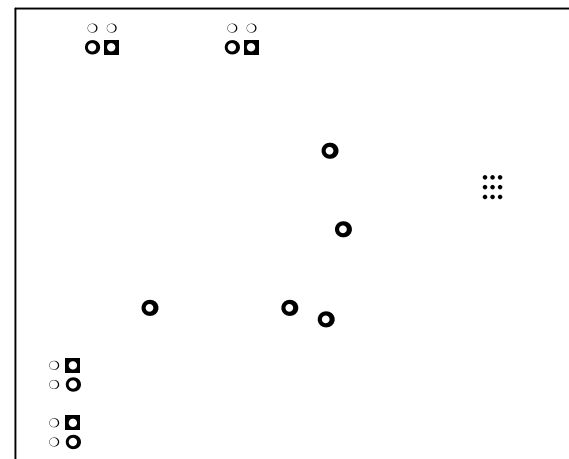
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01520	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01520		
PLOT NAME = Top Solder Mask	GENERATED : 12/12/2017 11:24:30 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01520	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01520		
PLOT NAME = Top Layer	GENERATED : 12/12/2017 11:24:31 AM	TEXAS INSTRUMENTS	



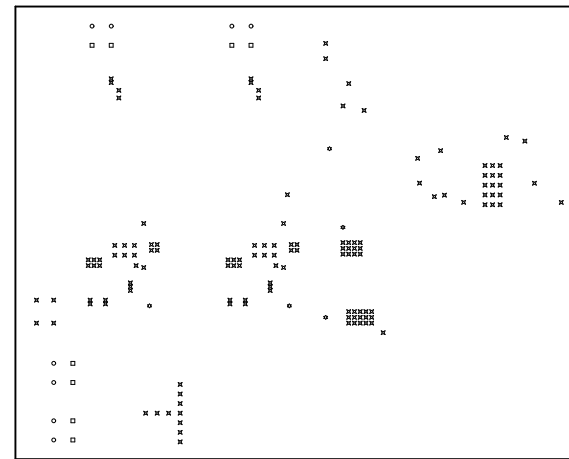
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01520	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01520		
PLOT NAME = Bottom Layer	GENERATED : 12/12/2017 11:24:32 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01520	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01520		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/12/2017 11:24:33 AM	TEXAS INSTRUMENTS	

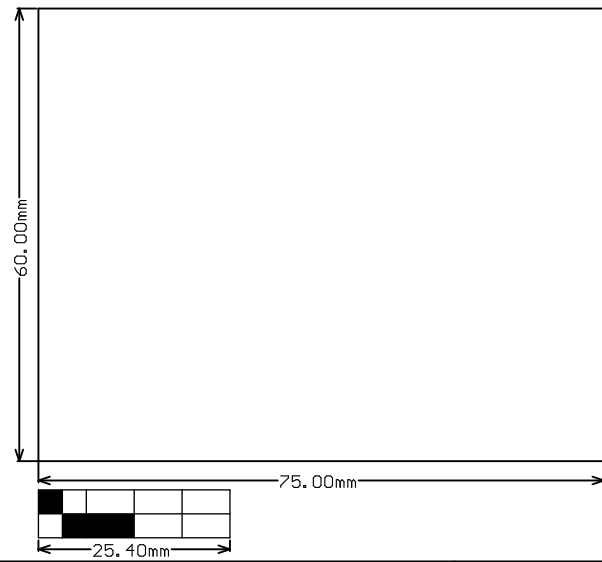


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01520	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01520		
PLOT NAME = Bottom Overlay	GENERATED : 12/12/2017 11:24:34 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Tolerance
○	8	43.31mil (1.100mm)	NPTH	Round	Top Layer - Bottom Layer	
⊗	133	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	5	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
□	8	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
	154 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01520	REV: B	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01520		
PLOT NAME = Drill Drawing	GENERATED : 12/12/2017 11:24:36 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01520	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01520		
PLOT NAME = Board Dimensions	GENERATED : 12/12/2017 11:24:38 AM	TEXAS INSTRUMENTS	

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